



BERGQUIST[®] GAP PAD[®] TGP 7000ULM

ULTRA-LOW MODULUS, HIGH THERMAL CONDUCTIVITY GAP FILLING MATERIAL

BERGQUIST[®] GAP PAD[®] TGP 7000ULM is a high thermal conductivity, ultra-low modulus thermal interface material designed for modern telecom and datacom applications where high power densities are the norm. The soft, conforming characteristics of BERGQUIST[®] GAP PAD[®] TGP 7000ULM ensure excellent wet out at the interface even on rough or irregular surfaces, delivering optimized thermal transfer and minimizing assembly stress. A silicone-based resin platform and unique filler technology enable high, 7.0 W/m-K thermal conductivity while prioritizing stress reduction on miniaturized, delicate components. BERGQUIST[®] GAP PAD[®] TGP 7000ULM is supplied in easy-to-use pre-cut pads and has an inherent high tack on both sides.



Key Benefits

- Low assembly stress due to ultra-low modulus (Shore 000, ASTM D2240)
- Excellent conformability to rough or irregular surfaces
- Thorough wet out at the interface for maximized thermal transfer
- High thermal conductivity of 7.0 W/m-K
- Simplified application and processability; supplied in pre-cut, custom-sized pads with high tack on both sides
- Room-temperature storage



	PROPERTIES	BERGQUIST® GAP PAD® TGP 7000ULM
Physical Properties	Young's Modulus (kPa)	152
	Appearance	Gray
Thermal Properties	Thermal Conductivity (W/m·K)	7.0
Electrical Properties	Dielectric Breakdown Voltage (40 mil, VAC)	> 5,000
	Volume Resistivity (Ω·m)	1.2 x 10 ¹¹
Safety Testing	Flammability Rating	UL 94 V-0

Typical applications

- Telecommunications (routers, switches and base stations)
- Optical Transceivers
- ASICs and DSPs



Across the Board,
Around the Globe. 
henkel-adhesives.com/thermal

Henkel Corporation
18930 West 78th Street
Chanhassen, MN 55317
United States
+1.800.347.4572

